

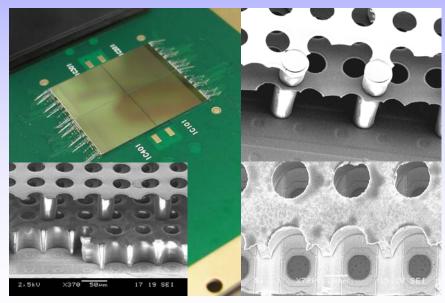
## Activities at NIKHEF for a Silicon TPC System

Jan Timmermans

## Work in progress

- (Post) processing in Twente.
  - Both SiNProt and InGrid can be applied.
  - Chip squares of 3X3 timepix chips instead of individual chips.
  - Search for high res InGrids.
    (Si<sub>3</sub>N<sub>4</sub>)
- Optimize protection and signal integrity.
  - Discharge test structures.

- Timepix2 chip
- Scaling up.
  - 4 chip detectors (3X3 cm).
  - 64 chip detector (12X12 cm).





## Multichip boards & Ingrids

- NIKHEF: 4-chip board (working in readout)
  Problems with power(regulation);
  being solved
- Recovering from problems with Ingrids production; delivering soon
- NIKHEF also aiming for 8x8-chip system in 2009/10